

WHAT IS CLAIMED IS:

1. A circuit device comprising:
a first circuit element having a hollow inside;
a plurality of second circuit elements electrically
5 connected to the first circuit element; and
sealing resin for covering the first and second circuit
elements,
wherein the distances by which the first circuit element
is separated from the second circuit elements are longer than
10 those by which the second circuit elements are separated from
each other.
2. The circuit device according to claim 1, wherein the
second circuit elements are located closer to a central portion
of the sealing resin than the first circuit element is.
- 15 3. The circuit device according to claim 1, wherein the
first circuit element is located closer to a peripheral portion
of the sealing resin than the second circuit elements are.
4. The circuit device according to claim 1, wherein the
first circuit element is a SAW filter.
- 20 5. A circuit device comprising:
a first circuit element having a hollow inside;
a second circuit element electrically connected to the
first circuit element; and
sealing resin for covering the first and second circuit
25 elements,
wherein the first circuit element is located closer to
a peripheral portion of the sealing resin than the second circuit
element is.

6. The circuit device according to claim 5, wherein the first circuit element is located in a vicinity of an end portion of the sealing resin in a longitudinal direction, and the second circuit element is located in a vicinity of a central portion of the sealing resin in the longitudinal direction.

7. The circuit device according to claim 5, further comprising:

the plurality of second circuit elements,

wherein the distances by which the first circuit element is separated from the second circuit elements are longer than those by which the second circuit elements are separated from each other.

8. The circuit device according to claim 5, wherein the first circuit element is a SAW filter.

9. A circuit device comprising:

a first circuit element fixed to a first land, the first circuit element having a hollow inside;

a second circuit element fixed to a second land located in a vicinity of a central portion away from the first land;

a first lead of which one end is led out to an outside and of which other end is connected to any one of the first and second circuit elements;

a second lead for connecting the first and second circuit elements; and

sealing resin for sealing the circuit elements and the leads.

10. The circuit device according to claim 9, wherein the first circuit element is a SAW filter.

11. The circuit device according to claim 9, wherein the second circuit element is any one of a semiconductor element for processing any one of a video signal and an image signal, a semiconductor element for processing information associated with the video signal, and a CCD for delaying an electrical signal.

12. The circuit device according to claim 9, wherein any one of the first and second circuit elements is connected to any one of the first and second leads through a fine metal wire.

13. A method of manufacturing a circuit device, comprising the steps of:

placing a first circuit element having a hollow inside and a second circuit element electrically connected to the first circuit element in a cavity of a molding die; and

sealing the first and second circuit elements with resin by filling sealing resin from a gate into the cavity,

wherein the first circuit element is located farther away from the gate than the second circuit element is.

14. The method according to claim 13,

wherein the cavity forms a long and narrow space,

the gate is formed in an end portion of the cavity in a longitudinal direction, and

the first circuit element is located in a vicinity of an end portion opposite to the gate inside the cavity.

15. The method according to claim 13, wherein thermosetting resin is adopted as the sealing resin.